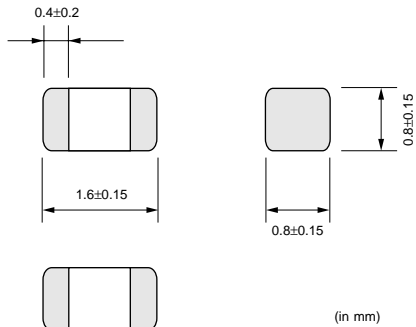


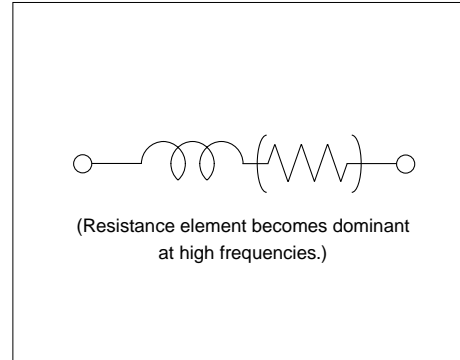
Chip EMIFIL[®] Inductor Type

BLM18P Series (0603 Size)

Dimension



Equivalent Circuit



Packaging

Code	Packaging	Minimum Quantity
D	180mm Paper Tape	4000
J	330mm Paper Tape	10000
B	Bulk(Bag)	1000

Rated Value (□: packaging code)

Part Number	Impedance (at 100MHz/20°C)	Impedance (at 1GHz/20°C)	Rated Current	DC Resistance(max.)	Operating Temperature Range	Number of Circuits
BLM18PG300SN1□	30ohm(Typ.)	-	1000mA	0.05ohm	-55°C to +125°C	1
BLM18PG330SN1□	33ohm±25%	-	3000mA	0.025ohm	-55°C to +125°C	1
BLM18PG600SN1□	60ohm(Typ.)	-	500mA	0.10ohm	-55°C to +125°C	1
BLM18PG121SN1□	120ohm±25%	-	2000mA	0.05ohm	-55°C to +125°C	1
BLM18PG181SN1□	180ohm±25%	-	1500mA	0.09ohm	-55°C to +125°C	1
BLM18PG221SN1□	220ohm±25%	-	1400mA	0.1ohm	-55°C to +125°C	1
BLM18PG331SN1□	330ohm±25%	-	1200mA	0.15ohm	-55°C to +125°C	1
BLM18PG471SN1□	470ohm±25%	-	1000mA	0.2ohm	-55°C to +125°C	1

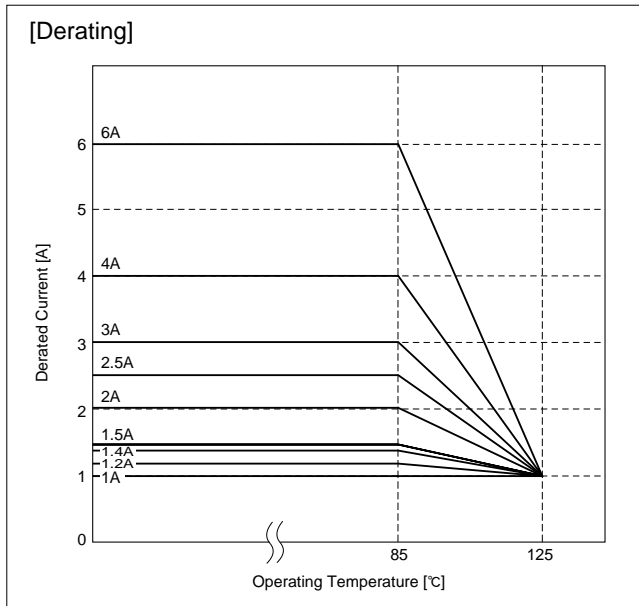
Continued on the following page.

● This data sheet is applied for CHIP FERRITE BEAD used for General Electronics equipment for your design.

Continued from the preceding page.

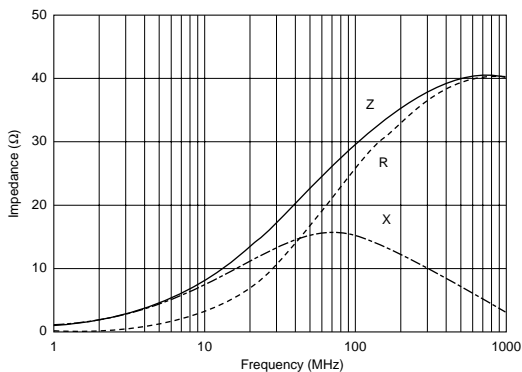
Notice (Rating)

In operating temperatures exceeding +85°C, derating of current is necessary for chip Ferrite Beads for which rated current is 1200mA or over. Please apply the derating curve shown in chart according to the operating temperature.



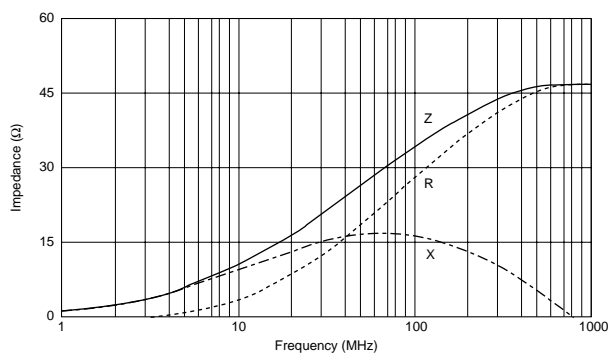
Z-f Characteristics (Typ.)

BLM18PG300SN1



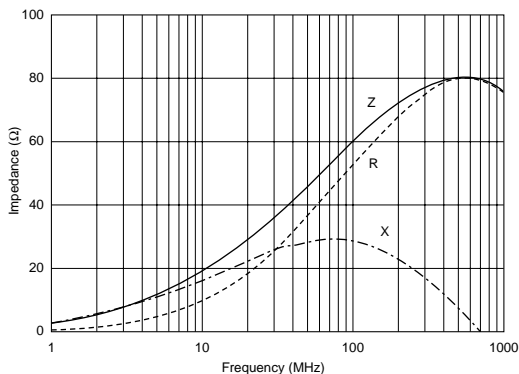
Z-f Characteristics(Typ.)

BLM18PG330SN1



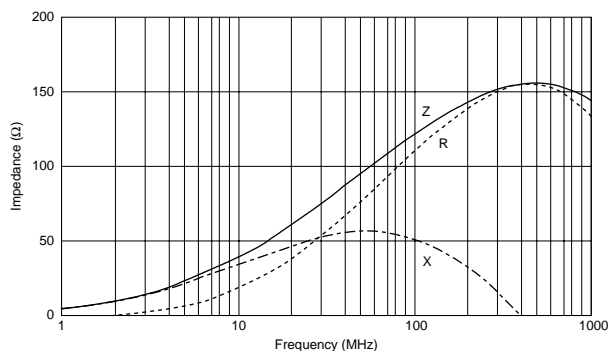
Z-f Characteristics (Typ.)

BLM18PG600SN1




Z-f Characteristics(Typ.)

BLM18PG121SN1



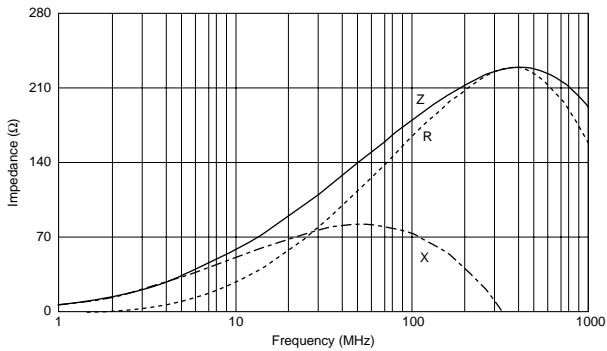
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● This data sheet is applied for CHIP FERRITE BEAD used for General Electronics equipment for your design.

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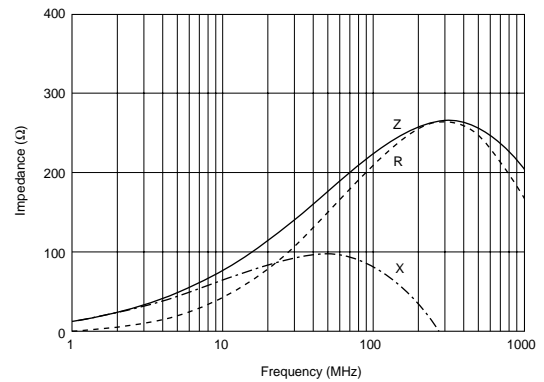
■ Z-f Characteristics(Typ.)

BLM18PG181SN1



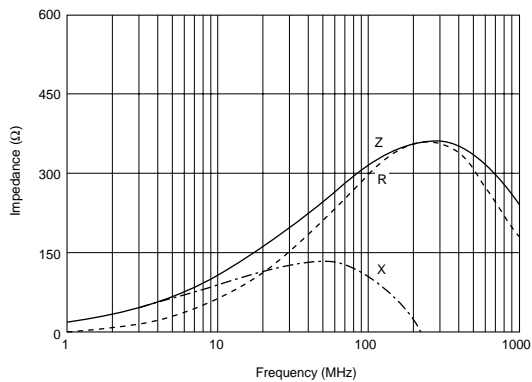
■ Z-f characteristics (Typ.)

BLM18PG221SN1



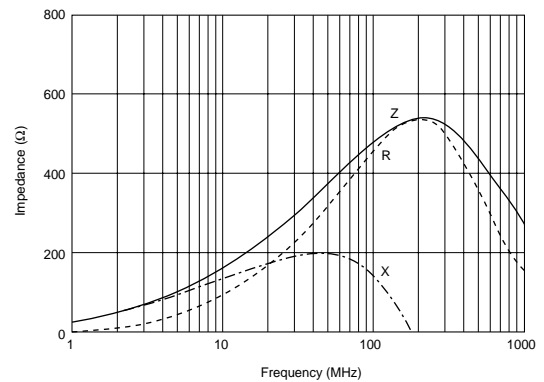
■ Z-f characteristics (Typ.)

BLM18PG331SN1



■ Z-f characteristics (Typ.)

BLM18PG471SN1



■ ⚠ Caution/Notice

⚠ Caution (Rating)

Do not use products beyond the rated current and rated voltage as this may create excessive heat and deteriorate the insulation resistance.

Notice

Solderability of Tin plating termination chip might be deteriorated when low temperature soldering profile where peak solder temperature is below the Tin melting point is used. Please confirm the solderability of Tin plating termination chip before use.

● This data sheet is applied for CHIP FERRITE BEAD used for General Electronics equipment for your design.

⚠ Note:

1. Export Control

〈For customers outside Japan〉

Murata products should not be used or sold for use in the development, production, stockpiling or utilization of any conventional weapons or mass-destructive weapons (nuclear weapons, chemical or biological weapons, or missiles), or any other weapons.

〈For customers in Japan〉

For products which are controlled items subject to the "Foreign Exchange and Foreign Trade Law" of Japan, the export license specified by the law is required for export.

2. Please contact our sales representatives or product engineers before using the products in this data sheet for the applications listed below, which require especially high reliability for the prevention of defects which might directly damage to a third party's life, body or property, or when one of our products is intended for use in applications other than those specified in this data sheet.

- | | |
|-----------------------------|---|
| ① Aircraft equipment | ② Aerospace equipment |
| ③ Undersea equipment | ④ Power plant equipment |
| ⑤ Medical equipment | ⑥ Transportation equipment (vehicles, trains, ships, etc.) |
| ⑦ Traffic signal equipment | ⑧ Disaster prevention / crime prevention equipment |
| ⑨ Data-processing equipment | ⑩ Application of similar complexity and/or reliability requirements to the applications listed in the above |

3. They are subject to change or our products in it may be discontinued without advance notice. Please check with our sales representatives or product engineers before ordering. If there are any questions, please contact our sales representatives or product engineers.

4. This data sheet has only typical specifications because there is no space for detailed specifications. Therefore, please approve our product specifications or transact the approval sheet for product specifications before ordering. Especially, please read rating and ⚠CAUTION (for storage, operating, rating, soldering, mounting and handling) in them to prevent smoking and/or burning, etc.

5. You are able to read a detailed specification in the website of Search Engine (<http://search.murata.co.jp/>) or catalog library (<http://www.murata.com/catalog/>) before to require our product specification or to transact the approval sheet for product specification.

6. Please note that unless otherwise specified, we shall assume no responsibility whatsoever for any conflict or dispute that may occur in connection with the effect of our and/or a third party's intellectual property rights and other related rights in consideration of your use of our products and/or information described or contained in our data sheets. In this connection, no representation shall be made to the effect that any third parties are authorized to use the right mentioned above under licenses without our consent.

7. No ozone depleting substances (ODS) under the Montreal Protocol are used in our manufacturing process.

● This data sheet is applied for CHIP FERRITE BEAD used for General Electronics equipment for your design.

● Part Numbering

Chip Ferrite Bead

(Part Number)

BL	M	18	AG	102	S	N	1	D
1	2	3	4	5	6	7	8	9

① Product ID

Product ID	
BL	Chip Ferrite Beads

② Type

Code	Type
A	Array Type
E	DC Bias Characteristics Improved Type
M	Ferrite Bead Single Type
T	Assembly Type

④ Characteristics/Applications

Code ^{*1}	Characteristics/Applications
AG	For General Use
AX	
TG	
BA	For High-speed Signal Lines
BB	
BC	
BD	
BX	
KD	
KG	For Power Lines
KN	
KX	
PD	
PG	
PN	
PS	
PX	
PT	
SD	
SG	For Digital Interface
SN	
SP	For GHz Band General Use
RK	
HG	For GHz Band High-speed Signal Lines (Low Direct Current Type)
EB	
EG	For GHz Band General Use (Low DC Resistance Type)
EX	
HB	For GHz Band High-speed Signal Lines
HD	
HE	
HK	For GHz Band Digital Interface
GA	For High-GHz Band High-speed Signal Lines
GG	For High-GHz Band General Use
DN	For High-GHz Band General Use (Low Direct Current Type)

*1 Frequency characteristics vary with each code.

③ Dimensions (LxW)

Code	Dimensions (LxW)	Size Code (inch)
02	0.4x0.2mm	01005
03	0.6x0.3mm	0201
15	1.0x0.5mm	0402
18	1.6x0.8mm	0603
2A	2.0x1.0mm	0804
21	2.0x1.25mm	0805
31	3.2x1.6mm	1206
32	3.2x2.5mm	1210
41	4.5x1.6mm	1806
5B	5.0x5.0mm	2020

⑤ Impedance

Expressed by three figures. The unit is in ohm (Ω) at 100MHz. The first and second figures are significant digits, and the third figure expresses the number of zeros that follow the two figures.

⑥ Electrode

Expressed by a letter.

Ex.)

Code	Electrode
S/F/T	Sn Plating
A	Au Plating
L	Lead Free Solder Plating

⑦ Category

Code	Category
N	For General

⑧ Number of Circuits

Code	Number of Circuits
1	1 Circuit
4	4 Circuits

⑨ Packaging

Code	Packaging
K	Embossed Taping (\varnothing 330mm Reel)
L	Embossed Taping (\varnothing 180mm Reel)
B	Bulk
J	Paper Taping (\varnothing 330mm Reel)
D	Paper Taping (\varnothing 180mm Reel)